

# Low Noise Amplifier for Ultra High Band 4-6GHz (f.e. LTE - U/ LAA with bypass)

#### **Features**

· Operating frequencies: 4.0 - 6.0 GHz

Insertion power gain: 13.7 dB

Insertion Loss in bypass mode: 7.5 dB

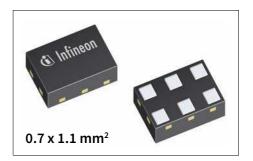
· Low noise figure: 1.6 dB

Low current consumption: 4.5 mA

• Multi-state control: OFF-, bypass- and high gain-Mode

Ultra small TSNP-6-2 leadless package

 RF input and RF output internally matched to 50 Ohm, no external components necessary



### **Application**

The LTE data rate can be significantly improved by using the Low Noise Amplifier. The integrated bypass function increases the overall system dynamic range and leads to more flexibility in the RF front-end.

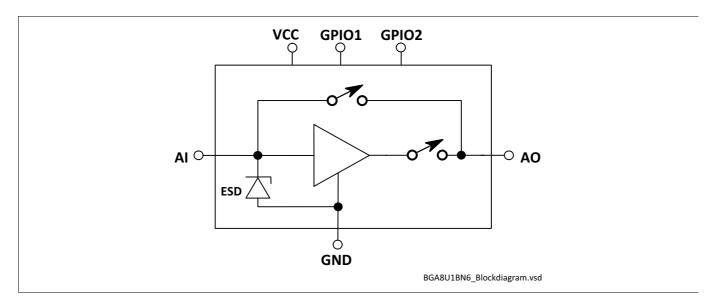
In high gain mode the LNA offers best Noise Figure to ensure high data rates even on the LTE cell edge. Closer to the basestation the bypass mode can be activated reducing current consumption.

The BGA8U1BN6 is designed for the inlicensed LTE spectrum (4-6GHz) part of the 3GPP Release 13.

#### **Product Validation**

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

### **Block diagram**



Data Sheet www.infineon.com

# Low Noise Amplifier for Ultra High Band 4-6GHz (f.e. LTE - U/ LAA with bypass)



### **Table of Contents**

# **Table of Contents**

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#### **Features**

### 1 Features

• Insertion power gain: 13.7 dB

• Insertion Loss in bypass mode: 7.5 dB

Low noise figure: 1.6 dB

Low current consumption: 4.5 mA

• Operating frequencies: 4.0 - 6.0 GHz

• Multi-state control: OFF-, bypass- and high gain-Mode

Supply voltage: 1.6 V to 3.1 V

Ultra small TSNP-6-2 leadless package (footprint: 0.7 x 1.1 mm²)

• B9HF Silicon Germanium technology

RF input and RF output internally matched to 50 Ohm

· No external SMD components necessary

• 2kV HBM ESD protection (including Al-pin)

• Pb-free (RoHS compliant) package





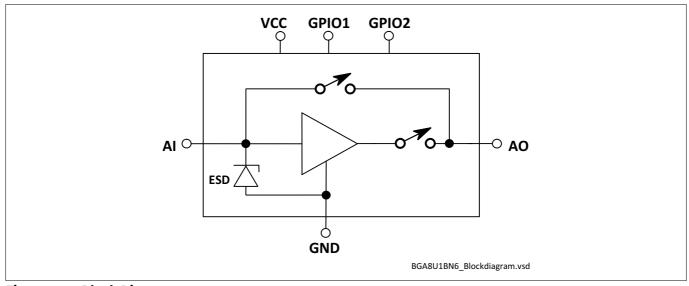


Figure 1 Block Diagram

Product Name	Marking	Package
BGA8U1BN6	Υ	TSNP-6-2

### Low Noise Amplifier for Ultra High Band 4-6GHz (f.e. LTE - U/LAA with bypass)



#### **Features**

### **Description**

The BGA8U1BN6 is a front-end low noise amplifier for LTE which covers a wide frequency range from 4.0 GHz to 6.0 GHz. The LNA provides 13.7 dB gain and 1.6 dB noise figure at a current consumption of 4.5 mA in the application configuration described in **Chapter 4**. In bypass mode the LNA provides an insertion loss of 7.5 dB. The BGA8U1BN6 is based upon Infineon Technologies' B7HF Silicon Germanium technology. It operates from 1.6 V to 3.1 V supply voltage. The device features a multi-state control (OFF-, bypass- and high gain-Mode).

#### **Pin Definition and Function**

Table 1 Pin Definition and Function

Pin No.	Name	Function
1	GPIO2	Control pin 2
2	VCC	DC supply
3	AO	LNA output
4	GPIO1	Control pin 1
5	GND	Ground
6	Al	LNA input

### **Control Table**

Table 2 Control Table

	GPI01	GPIO2
OFF	Low	Low
	High	Low
Bypass mode	Low	High
High gain mode	High	High

### Low Noise Amplifier for Ultra High Band 4-6GHz (f.e. LTE - U/LAA with bypass)



**Maximum Ratings** 

# 2 Maximum Ratings

Table 3 Maximum Ratings

Parameter	Symbol	Symbol Values				Note or	
		Min.	Тур.	Max.		<b>Test Condition</b>	
Voltage at pin VCC	$V_{\rm cc}$	-0.3	_	3.6	V	1)	
Voltage at pin Al	$V_{AI}$	-0.3	-	0.9	V	_	
Voltage at pin AO	$V_{AO}$	-0.3	-	V <sub>CC</sub> + 0.3	V	_	
Voltage at GPIO pins	$V_{GPIO}$	-0.3	-	V <sub>CC</sub> + 0.3	V	_	
Voltage at pin GND	$V_{\sf GND}$	-0.3	-	0.3	V	_	
Current into pin VCC	I <sub>cc</sub>	_	-	16	mA	_	
RF input power	P <sub>IN</sub>	_	-	+25	dBm	_	
Total power dissipation, $T_S < 148  ^{\circ}C^{2)}$	P <sub>tot</sub>	_	-	60	mW	-	
Junction temperature	$T_{J}$	_	-	150	°C	_	
Ambient temperature range	$T_{A}$	-40	_	85	°C	-	
Storage temperature range	$T_{\rm STG}$	-65	_	150	°C	-	
ESD capability all pins	V <sub>ESD_HBM</sub>	-2000	-	+2000	V	according to JS-001	

<sup>1)</sup> All voltages refer to GND-Node unless otherwise noted

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit. Exposure to conditions at or below absolute maximum rating but above the specified maximum operation conditions may affect device reliability and life time. Functionality of the device might not be given under these conditions.

<sup>2)</sup>  $T_S$  is measured on the ground lead at the soldering point

### Low Noise Amplifier for Ultra High Band 4-6GHz (f.e. LTE - U/LAA with bypass)



#### **Electrical Characteristics**

### 3 Electrical Characteristics

Table 4 Electrical Characteristics1)

 $T_{\rm A}$  = 25 °C,  $V_{\rm CC}$  = 1.8 V,  $V_{\rm GPIOx,ON}$  = 1.8 V,  $V_{\rm GPIOx,OFF}$  = 0 V, f = 4000 - 6000 MHz

Parameter	Symbol	Values			Unit	<b>Note or Test Condition</b>
		Min.	Тур.	Max.		
Supply voltage	$V_{CC}$	1.6	1.8	3.1	V	-
Control voltages	$V_{\rm GPIOx}$	1.0	_	$V_{\rm cc}$	V	High
		0	_	0.4	V	Low
Supply current	I <sub>cc</sub>	_	4.3	5.3	mA	High gain mode
		_	85	120	μΑ	Bypass mode
		_	0.1	2	μΑ	OFF-Mode
Insertion power gain	$ S_{21} ^2$	10.9	13.4	15.9	dB	High gain mode
f=5500 MHz		-9.5	-7.5	-5.5	dB	Bypass mode
Noise figure <sup>2)</sup>	NF	_	1.65	2.55	dB	High gain mode
$f = 5500 \text{ MHz}, Z_{S} = 50 \Omega$		_	7.5	9.5	dB	Bypass mode
Input return loss <sup>3)</sup>	RL <sub>IN</sub>	9	13	_	dB	High gain mode
f = 5500 MHz		7	11	_	dB	Bypass mode
Output return loss <sup>3)</sup>	RL <sub>OUT</sub>	12	20	_	dB	High gain mode
f = 5500 MHz		3	4	_	dB	Bypass mode
Reverse isolation <sup>3)</sup>	1/ S <sub>12</sub>   <sup>2</sup>	20	28	_	dB	High gain mode
f = 5500 MHz		5.5	7.5	-	dB	Bypass mode
Transient time $C_1 = 1 \text{ nF}^{4)6}$	t <sub>S</sub>	_	0.3	3	μs	High gain- to bypass-mode
		_	12	15	μs	Bypass- to High gain-mode
Transient time $C_1 = 33 \text{ pF}^{4)6}$	t <sub>S</sub>	_	0.3	3	μs	High gain- to bypass-mode
		_	1	3	μs	Bypass- to High gain-mode
Inbandinput 1dB-compression	$IP_{1dB}$	-22	-18	-	dBm	High gain mode
point, <i>f</i> = 5500 MHz <sup>3)</sup>		-8	-4	-	dBm	Bypass mode
Inband input 3 <sup>rd</sup> -order	IIP <sub>3</sub>	-16	-11	_	dBm	High gain mode $C_1 = 1$ nF
intercept point <sup>3)5)</sup> $f_1 = 5500 \text{ MHz}, f_2 = f_1 + / - 1 \text{ MHz}$		-1	4	_	dBm	Bypass mode $C_1 = 1 \text{ nF}$
Phase discontinuity between ON- and bypass-mode <sup>3)</sup>		-6	-	6	o	Part to part variation after compensation in Base Band with constant value
Stability <sup>6)</sup>	k	> 1	-	_		f = 20 MHz 10 GHz

- 1) Based on the application described in chapter 4
- 2) PCB losses are subtracted
- 3) Verification based on AQL; not 100% tested in production
- 4) To be within 1 dB of the final gain
- 5) Input power HG = -30 dBm for each tone; input power BP = -10 dBm for each tone
- 6) Guaranteed by device design; not tested in production

### Low Noise Amplifier for Ultra High Band 4-6GHz (f.e. LTE - U/LAA with bypass)



#### **Electrical Characteristics**

### Table 5 Electrical Characteristics<sup>1)</sup>

 $T_{\rm A}$  = 25 °C,  $V_{\rm CC}$  = 2.8 V,  $V_{\rm GPIOx,ON}$  = 2.8 V,  $V_{\rm GPIOx,OFF}$  = 0 V, f = 4000 - 6000 MHz

Parameter	Symbol	Values			Unit	Note or Test Condition
		Min.	Тур.	Max.		
Supply voltage	$V_{cc}$	1.6	2.8	3.1	V	-
Control voltages	$V_{\rm GPIOx}$	1.0	_	V <sub>cc</sub>	V	High
		0	_	0.4	V	Low
Supply current	I <sub>cc</sub>	_	4.5	5.5	mA	High gain mode
		-	85	120	μΑ	Bypass mode
		_	0.1	2	μΑ	OFF-Mode
Insertion power gain	$ S_{21} ^2$	11.2	13.7	16.2	dB	High gain mode
f = 5500 MHz		-9.5	-7.5	-5.5	dB	Bypass mode
Noise figure <sup>2)</sup>	NF	_	1.6	2.5	dB	High gain mode
$f = 5500 \text{ MHz}, Z_{S} = 50 \Omega$		-	7.5	9.5	dB	Bypass mode
Input return loss <sup>3)</sup>	RL <sub>IN</sub>	9	13	_	dB	High gain mode
f=5500 MHz		7	11	_	dB	Bypass mode
Output return loss <sup>3)</sup>	RL <sub>OUT</sub>	12	20	_	dB	High gain mode
f=5500 MHz		3	4	_	dB	Bypass mode
Reverse isolation <sup>3)</sup>	$1/ S_{12} ^2$	20	28	_	dB	High gain mode
f=5500 MHz		5.5	7.5	_	dB	Bypass mode
Transient time $C_1 = 1 \text{ nF}^{4)6}$	$t_{S}$	_	0.3	3	μs	High gain- to bypass-mode
		-	7	10	μs	Bypass- to High gain-mode
Transient time $C_1 = 33 \text{ pF}^{4)6)}$	t <sub>S</sub>	_	0.3	3	μs	High gain- to bypass-mode
		-	0.9	3	μs	Bypass- to High gain-mode
Inbandinput 1dB-compression	IP <sub>1dB</sub>	-22	-18	_	dBm	High gain mode
point, f = 5500 MHz <sup>3)</sup>		-8	-4	_	dBm	Bypass mode
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Stability <sup>6)</sup>	k	> 1	_	_		f = 20 MHz 10 GHz

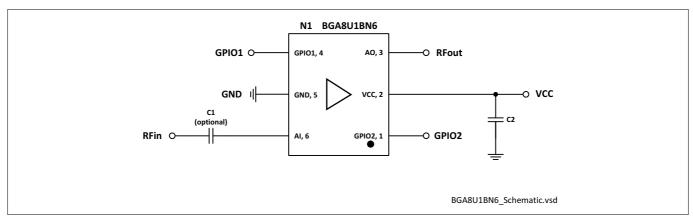
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**Application Information** 

#### **Application Information** 1

### **Application Board Configuration**



**Application Schematic BGA8U1BN6** Figure 1

Table 1 **Bill of Materials** 

Name	Value	Package	Manufacturer	Function
C1 (optional)	1nF/33pF	0402	Various	DC block <sup>1)</sup>
C2 (optional)	≥ 1nF	0402	Various	RF bypass <sup>2)</sup>
N1	BGA8U1BN6	TSNP-6-2	Infineon	SiGe LNA

No external DC block is needed if there is pre-filter implemented. DC block capacitor of less or equal than 100 pF is recommended to reduce the switching time during the mode transition.

A list of all application notes is available at http://www.infineon.com/ltelna

<sup>2)</sup> RF bypass recommended to mitigate power supply noise



**Package Information** 

# 1 Package Information

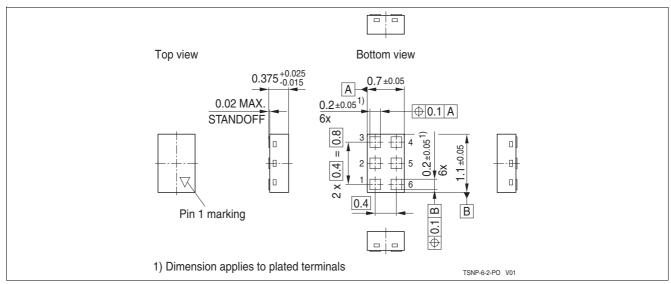


Figure 1 TSNP-6-2 Package Outline (top, side and bottom views)

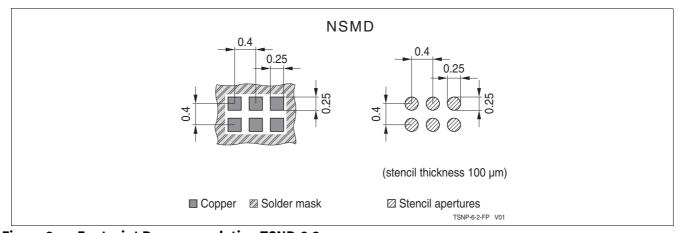
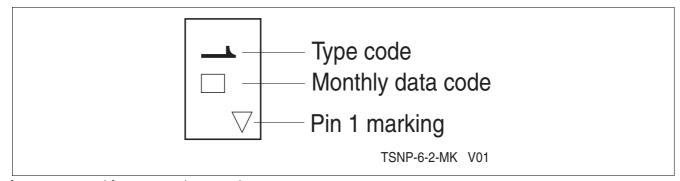


Figure 2 Footprint Recommendation TSNP-6-2



**Figure 3** Marking Layout (top view)

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### **Package Information**

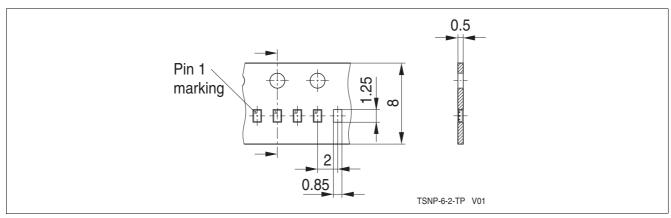


Figure 4 Tape & Reel Dimensions (reel diameter 180 mm, pieces/reel 15000)





Revision History						
Page or Item	Subjects (major changes since previous revision)					
Revision 3.2, 2021-04-19						
6	Add Electrical Characterisation for Vcc=1.8V					
7	Update Transient Time Information					
8	Update Application Information					

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